



US00D471165S

(12) **United States Design Patent** (10) **Patent No.:** **US D471,165 S**
Williams et al. (45) **Date of Patent:** **** *Mar. 4, 2003**

(54) **SURFACE MOUNT PACKAGE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/141,963**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; D14/114; 257/621, 666, 669, 672, 673, 674, 676, 684-690, 692, 696, 710, 711, 730, 731; 361/718, 742, 760, 774, 820

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(57) **CLAIM**

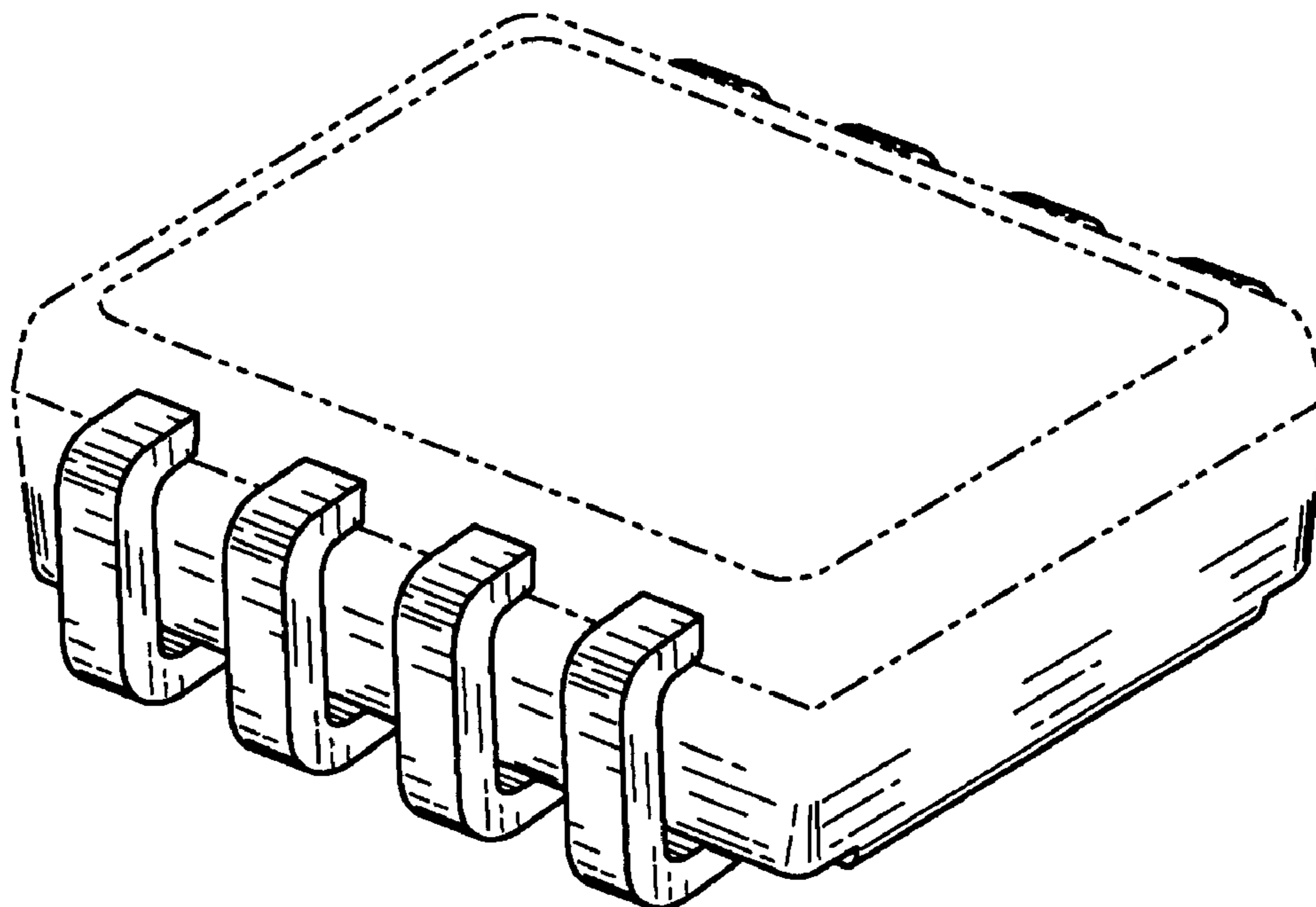
The ornamental design for a surface mount package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a surface mount package showing our new design;
 FIG. 2 is a top plan view thereof;
 FIG. 3 is a bottom plan view thereof;
 FIG. 4 is a front elevational view thereof;
 FIG. 5 is a rear elevational view thereof;
 FIG. 6 is a left side elevational view thereof; and,
 FIG. 7 the right side elevational view thereof.

The broken line showing of the environment is for illustrative purpose only and forms no part of the claimed design.

1 Claim, 3 Drawing Sheets



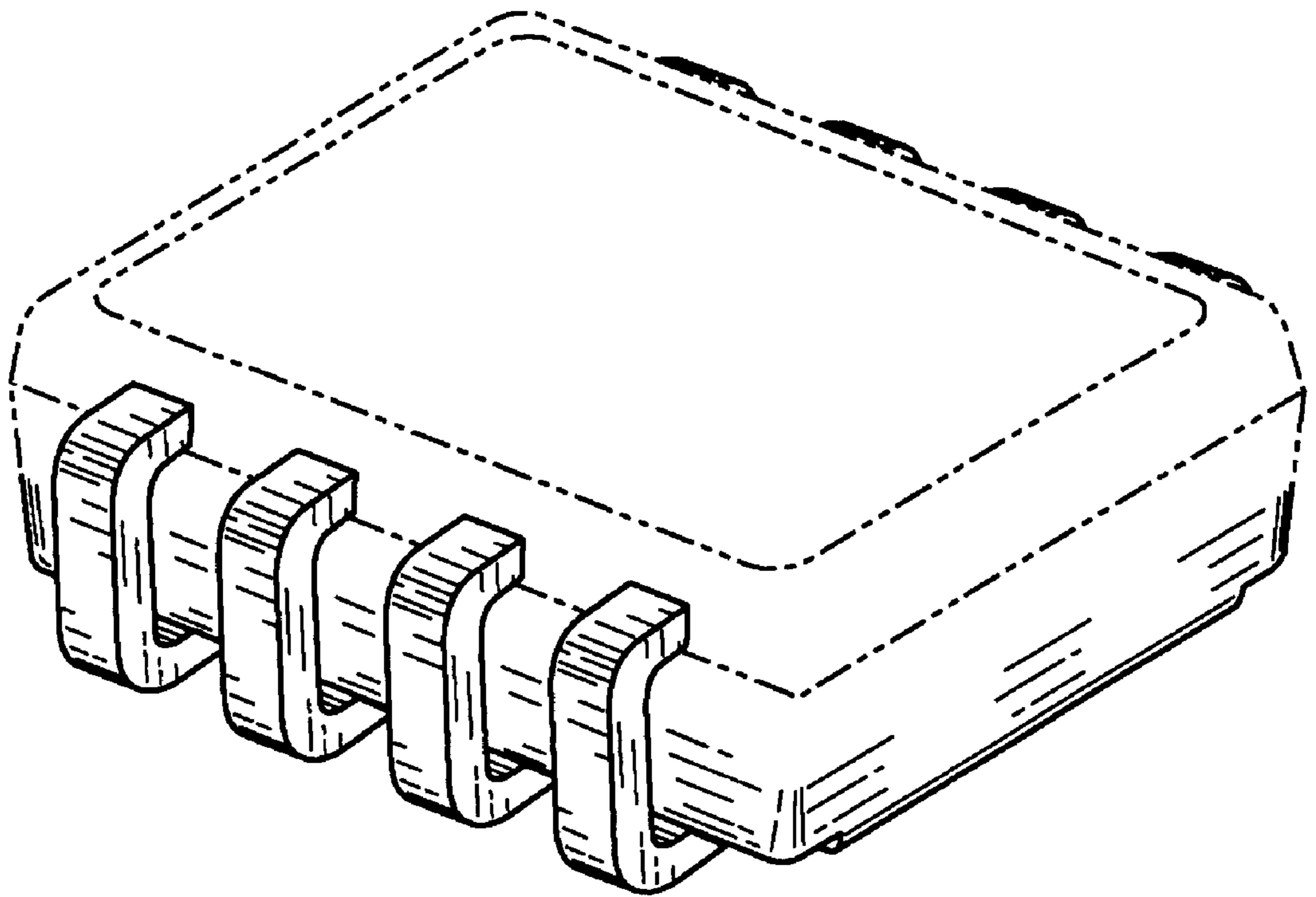


FIG. 1

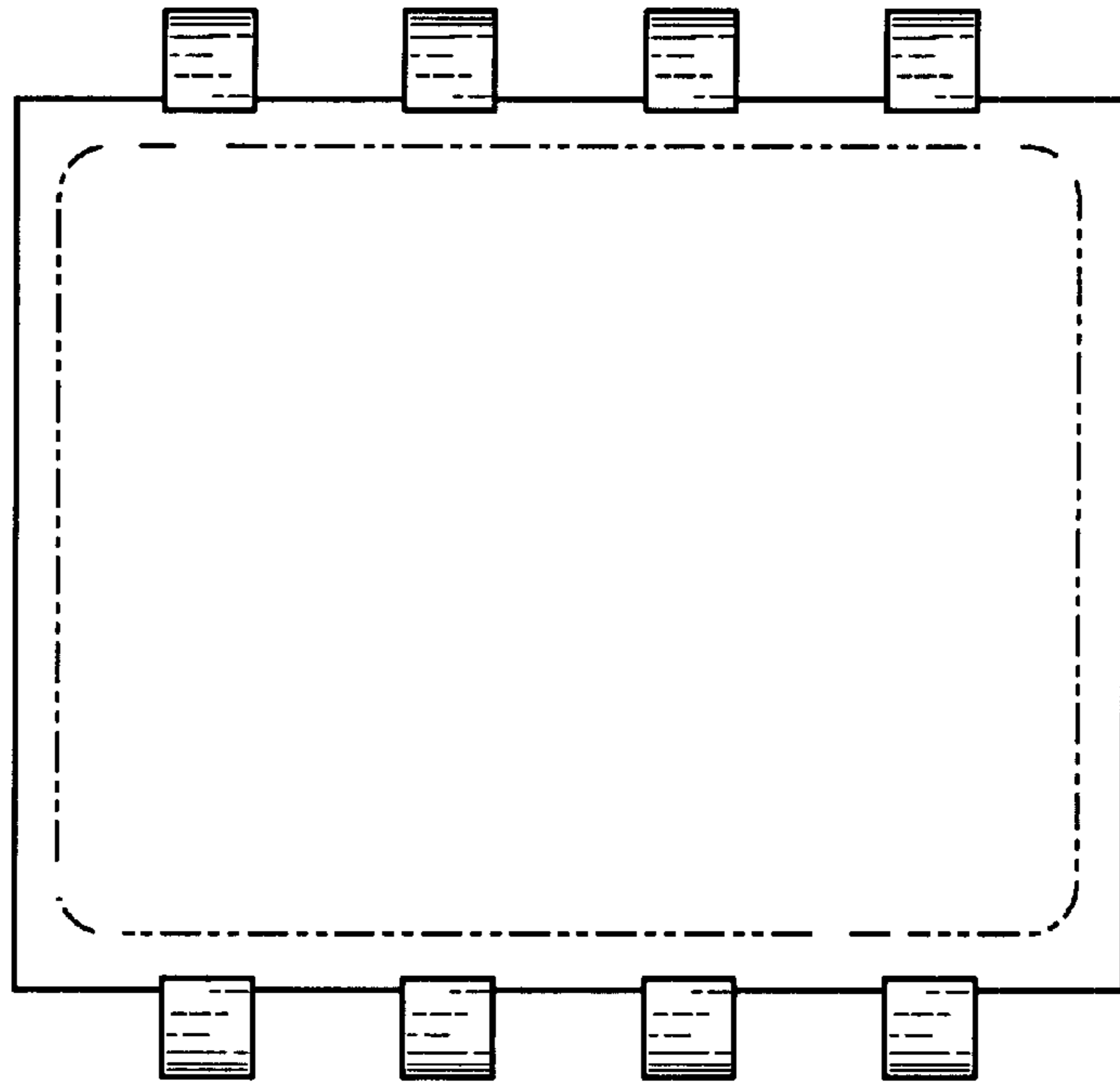


FIG. 2

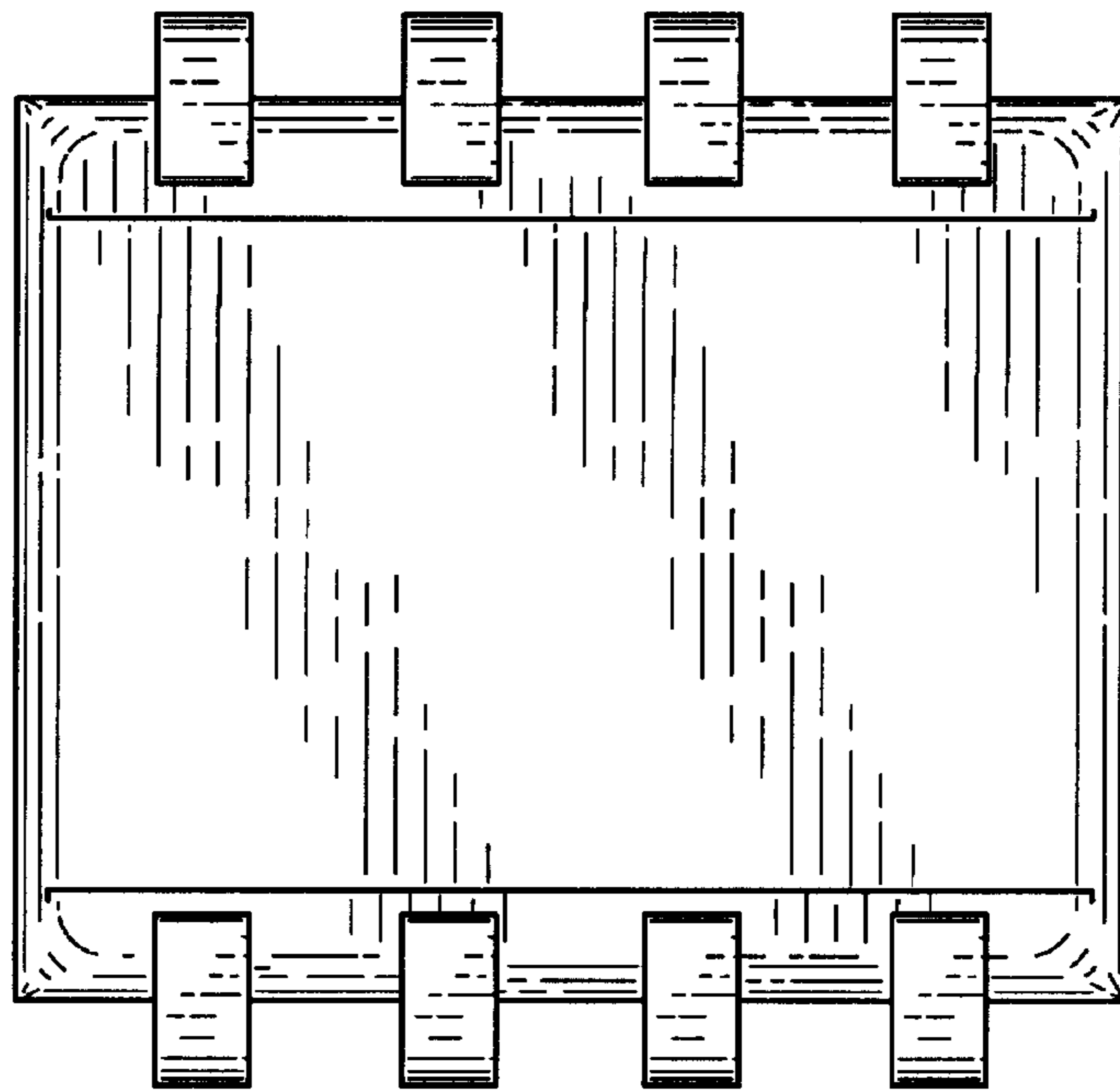


FIG. 3

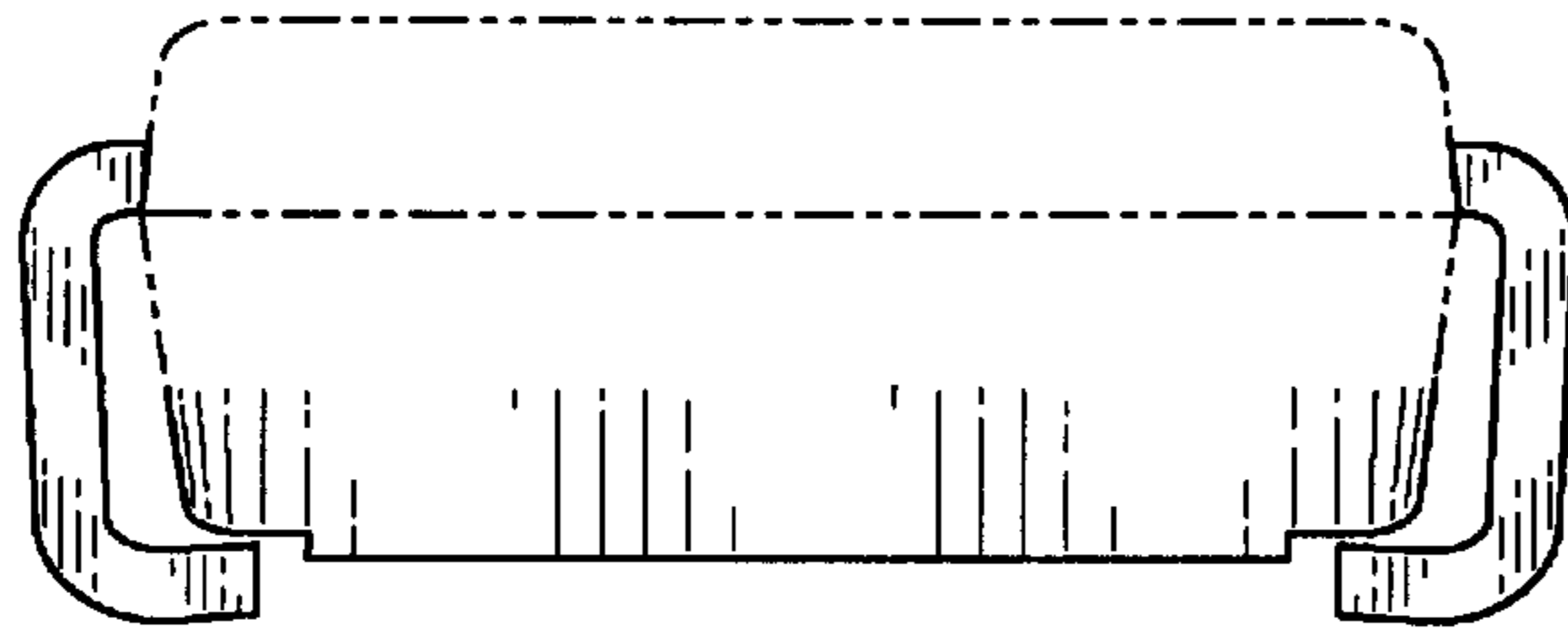


FIG. 4

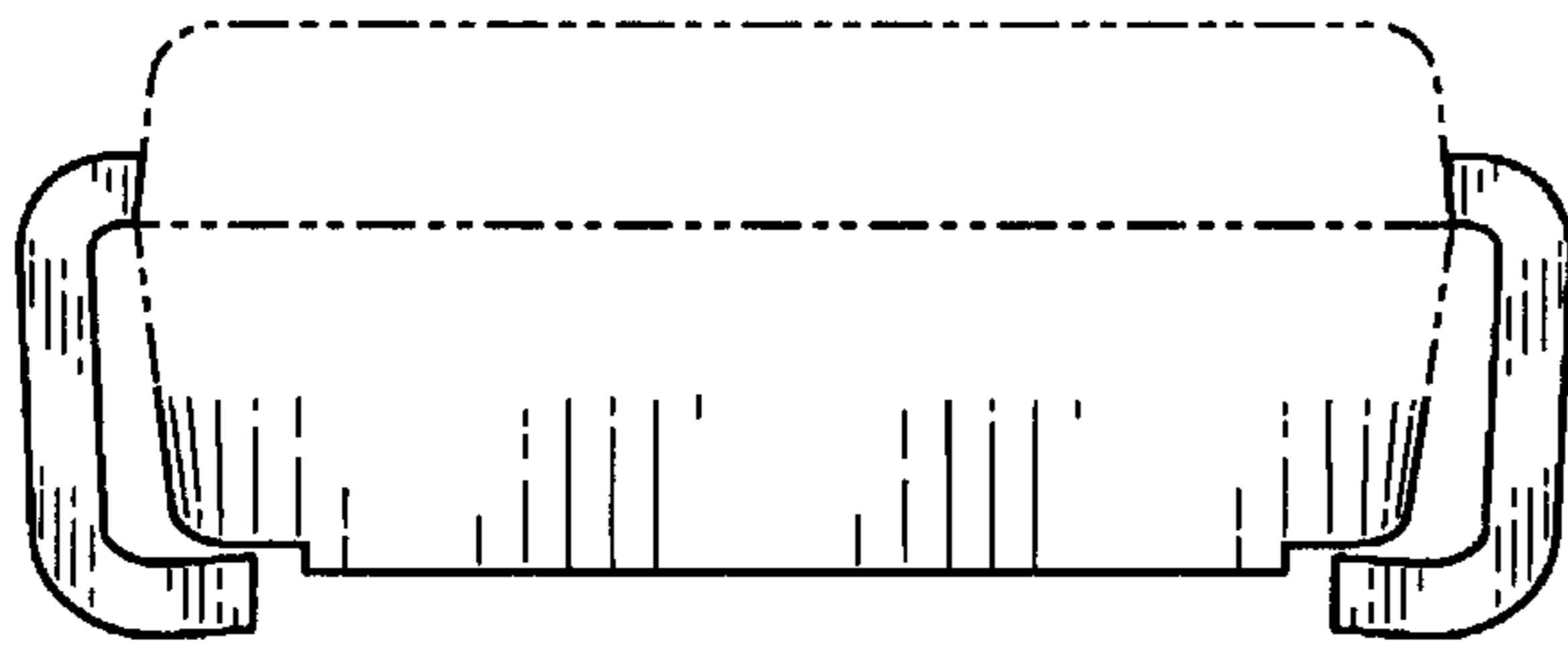


FIG. 5

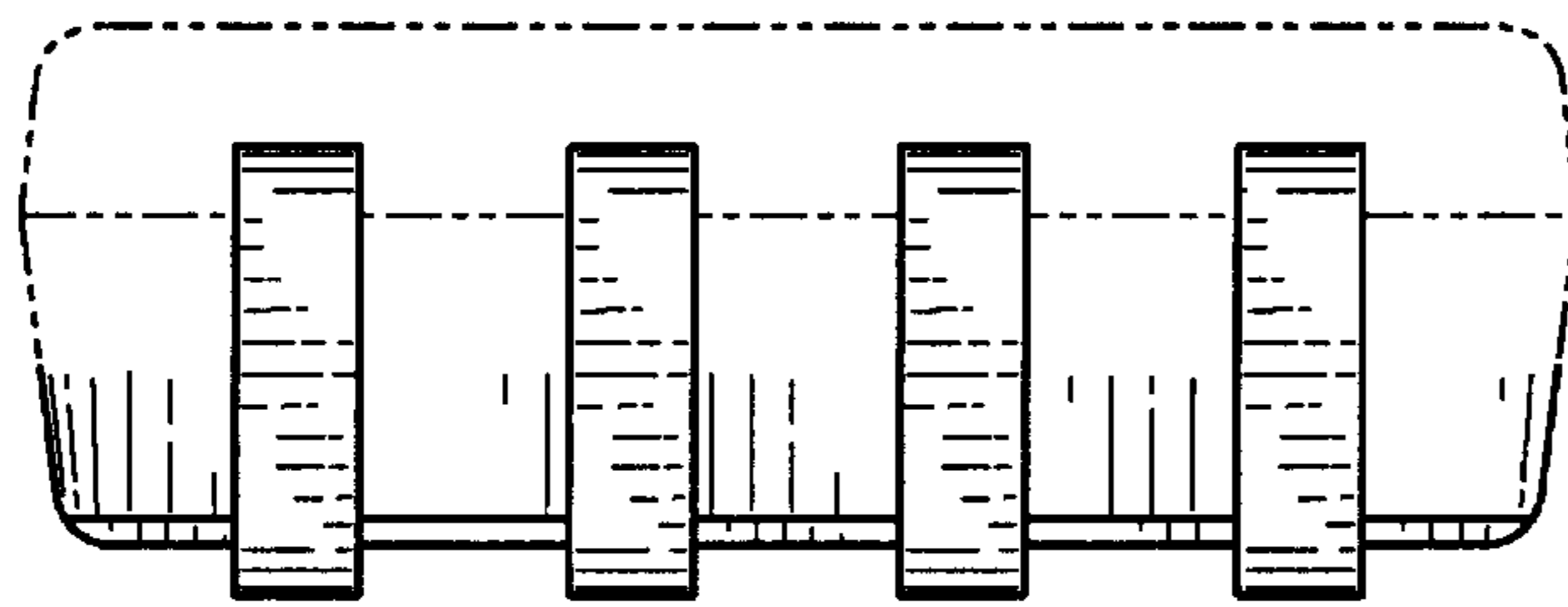


FIG. 6

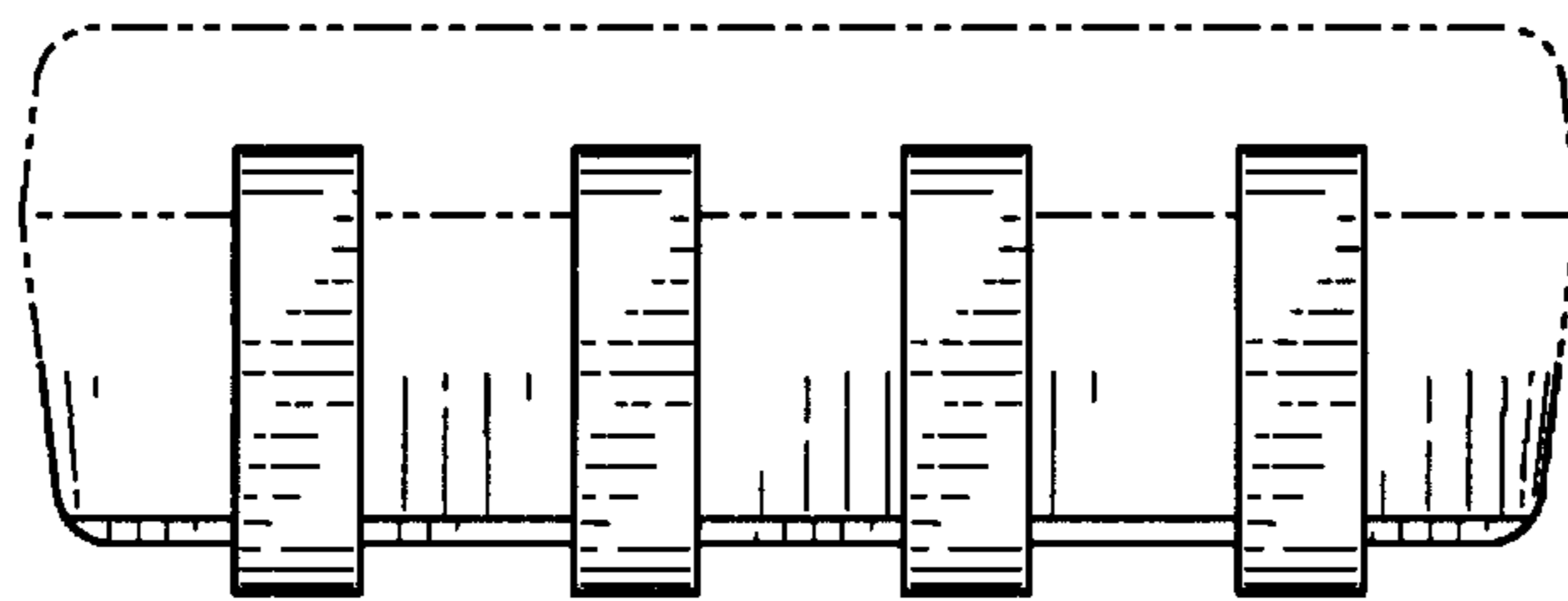


FIG. 7